

**18:30-20:30 Panel Discussion (Intl. Conference Room)**

**"What Can Computer Aided Engineering Do for the SoC Era ?"**

Moderators: H. Masuda, *STARC*

M. Orłowski, *Motorola*

Panelists: R.W. Dutton, *Stanford Univ.*

M. Fukuma, *NEC*

S.-W. Lee, *Intel*

W. Schoenmaker, *IMEC*

S. Selberherr, *Wien Inst. Tech.*

T. Wada, *Toshiba*

TCAD has contributed to process/device design and prediction of the device performances for decades. This role is still very important in very deep submicron process; however, new aspect in the semiconductor industry has arisen.

Interconnect issue becomes more critical in SoC timing closure. ITRS roadmap predicts future of process/devices and interconnects, which lead to a standardized process and device. TCAD seems to be requested to contribute in the new situation of SoC era.

The panel addresses topics such as:

What is the new role of TCAD in SoC era? How TCAD can contribute towards the ultimate-solution in timing closure problem.

How to attack SI(Signal Integrity) Physical Design by TCAD.

Can TCAD make innovation on Process & Device, which changes the ITRS2001?